

**COMPONENT AND METHOD FOR
MANUFACTURING PRINTED CIRCUIT BOARDS**

ABSTRACT OF THE DISCLOSURE

above-mentioned need is met by the present invention, which provides a laminated component including a separator having first and second surfaces, a conductive film layer disposed against the first surface of the separator, and a non-conductive film layer disposed against the second surface of the separator. The conductive and non-conductive film layers both have larger lateral dimensions than the separator such that a portion of each film layer extends beyond the separator. The extending portions of the conductive and non-conductive film layers are joined together to seal the laminated component. In one embodiment, a band of adhesive is disposed on a first surface of the conductive film layer so as to define an enclosed central area inwardly thereof and the separator is placed within the central area. The extending portion of the non-conductive film layer is pressed against the adhesive to form a joint between the conductive film layer and the non-conductive film layer.